



LTM2885-BGA-32LD-PBF 22mm X 9mm X 5.06mm (TABLE OF MATERIAL DECLARATION)

The LTM2885 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2326	Copper	7440-50-8	0.05051	21.716%
				Gold	7440-57-5	0.00004	0.019%
				Palladium	7440-50-3	0.00003	0.012%
				Nickel	7440-02-0	0.00149	0.642%
				Cured thermosetting resin (including inorganic filler)	non-disclosure	0.02776	11.935%
				Continuous Filament Fiber Glass	65997-17-3	0.02776	11.935%
				Copper	7440-50-8	0.03701	15.914%
				Thermosetting resin (including inorganic filler)	non-disclosure	0.04442	19.096%
				Continuous Filament Fiber Glass	65997-17-3	0.02961	12.731%
				Cured Resin	non-disclosure	0.00860	3.696%
				Phthalocyanine blue	147-14-8	0.00002	0.009%
				Organic pigment	non-disclosure	0.00002	0.009%
				Silica	7631-86-9	0.00128	0.552%
				Barium sulfate	7727-43-7	0.00128	0.552%
				Talc	14807-96-6	0.00128	0.552%
Organic filler	non-disclosure	0.00128	0.552%				
Antifoamer and Leveling agent	non-disclosure	0.00018	0.078%				
2	Solder Paste	Alloy	0.0652	Sn	7440-31-5	0.06197	95.0
				Sb	7440-36-0	0.00326	5.0
3	Epoxy		0.0033	Di-ester resin	non-disclosure	0.00033	10.00
				Functionalized ester	non-disclosure	0.00033	10.00
				Silver	7440-22-4	0.00262	80.00
4	Passive/Active Components		0.1793	Capacitor	-	0.05860	32.7
				Resistor	-	0.00093	0.5
				Inductor	-	0.11976	66.8
				Diode	-	0.00000	0.0
5	Active Ics	Silicon	0.0027	Silicon	7440-21-3	0.00273	100
6	Wire	Gold	0.0010	Au	7440-57-5	0.10457	99.99
7	Solder Ball	SAC305	0.0243	Sn	7440-31-5	0.00101	96.5
				Ag	7440-22-4	0.00003	3
				Cu	7440-50-8	0.00001	0.5
8	Encapsulation	Epoxy Resin	1.4761	Fused Silica	60676-86-0	1.13952	77.2
				Epoxy Resin	non-disclosure	0.13137	8.9
				Phenol Resin	non-disclosure	0.13137	8.9
				Crytalline Silica	14808-60-7	0.04428	3.0
				Carbon Black	1333-86-4	0.00738	0.5
				Metal Hydroxide	non-disclosure	0.02214	1.5
Total Package Weight			1.9846				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts